

K3273-VB Datasheet N-Channel 60 V (D-S) MOSFET

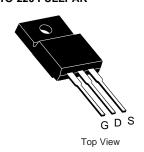
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a			
60	0.005 at V _{GS} = 10 V	120			
00	0.013 at $V_{GS} = 4.5 \text{ V}$	95			

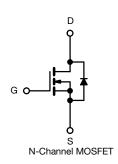
FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:



TO-220 FULLPAK





ABSOLUTE MAXIMUM RATINGS (T_C =	= 25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
On the same Preside Output (T. 175 20)b	T _C = 25 °C		120	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C	l lD	95 ^a	
Pulsed Drain Current	<u>.</u>	I _{DM}	300	А
Continuous Source Current (Diode Conduction)		I _S	70 ^a	
Avalanche Current		I _{AS}	50	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	125	mJ
Manifestor Branco Biodination	T _C = 25 °C	P _D	136	W
Maximum Power Dissipation	T _A = 25 °C] 'D [3 ^b , 8.3 ^{b, c}	
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R_{thJA}	15	18	°C/W		
waximum Junction-to-Ambient*	Steady State		40	50			
Maximum Junction-to-Case		R_{thJC}	0.85	1.1			

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			\/	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = 60 V, V _{GS} = 0 V	1		1		
	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	50 μA	
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α	
		V _{GS} = 10 V, I _D = 20 A		0.005			
D : 0	D	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.010		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.015	2		
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.013			
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		60		S	
Dynamic			•	•			
Input Capacitance	C _{iss}			5650			
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		1120		pF	
Reverse Transfer Capacitance	C _{rss}			525			
Total Gate Charge ^c	Q_g			47	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		10		nC	
Gate-Drain Charge ^c	Q_{gd}			12			
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 0.6 \Omega$ $I_D \cong 50 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 2.5 \Omega$		15	25	20	
Turn-Off Delay Time ^c	t _{d(off)}			35	50	ns	
Fall Time ^c	t _f]		20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)		_			
Pulsed Current	I _{SM}			300		Α	
Diode Forward Voltage	V _{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		45	100	ns	

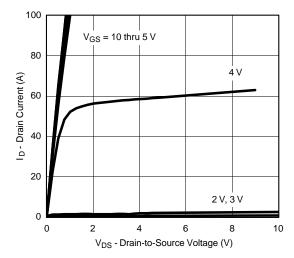
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

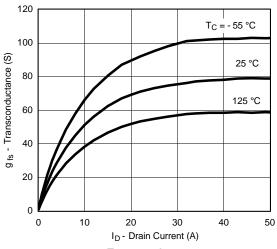
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



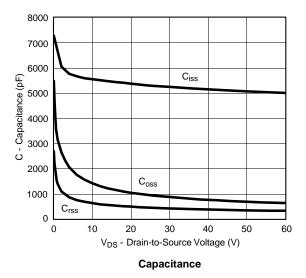
TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



Transconductance



100

80

(V) triangle 60

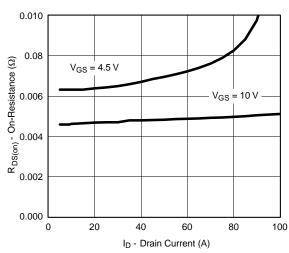
T_C = 125 °C

25 °C

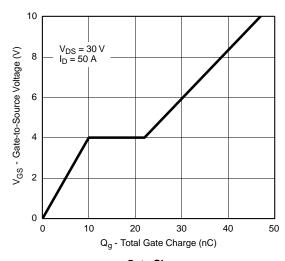
-55 °C

V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



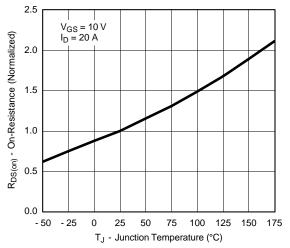
On-Resistance vs. Drain Current



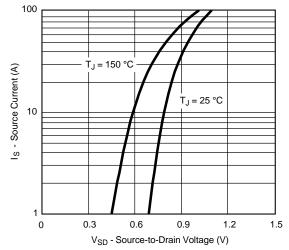
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

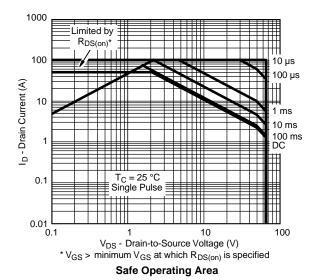


Source-Drain Diode Forward Voltage

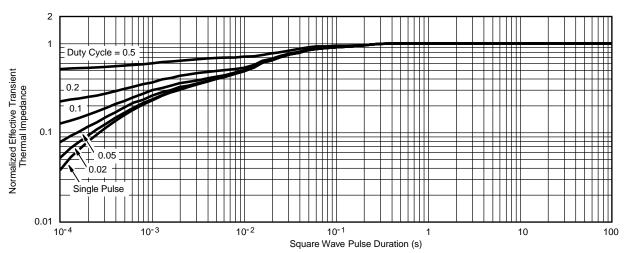


THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



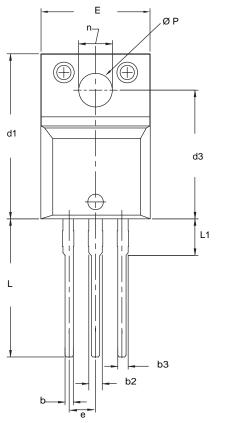
Normalized Thermal Transient Impedance, Junction-to-Case

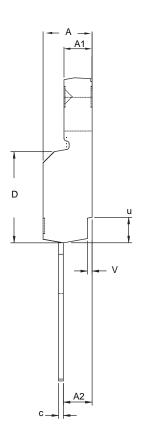
服务热线:400-655-8788

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TO-220 FULLPAK (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

ECN: X09-0126-Rev. B, 26-Oct-09 DWG: 5972

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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